



# 3D Packaging and Integration Japan TC Chapter

Japan Standards Spring Meetings 2024

Thursday, May 23, 2024

Room 1, SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting

14:00–16:00 (JST)

## AGENDA

### 1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

### 2 Review of Previous Meeting Minutes

### 3 Liaison Report

- 3.1 JRSC Report
- 3.2 GCS Report
- 3.3 North America TC Chapter
- 3.4 Taiwan TC Chapter

### 4 Staff Report

### 5 Ballot Review

None

### 6 Subcommittee & Task Force Reports

- 6.1 3DS IC Bonded Layer Inspection Metrology Task Force
- 6.2 Wafer Bond Strength Measurement by Double-cantilever Beam Task Force
- 6.3 3D Packaging & Integration 5-Year Review Task Force
- 6.4 3D Packaging & Integration Steering Group



## 7 Old Business

### 7.1 Project Period Review

### 7.2 5-Year Review

- SEMI G96-1014 (Reapproved 1019), Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending
- SEMI 3D19-0619, Test Method for Adhesive Strength of Adhesive Tray Used for Thin Chip Handling

## 8 New Business

### 8.1 Program at SEMICON Japan 2024

## 9 Action Item Review

### 9.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
20240126-01	SEMI Staff	To prepare SNARFs for Reapproval documents by next TC Meeting.
20240126-02	SEMI Staff	To inform the ballot template to the TF leader.

### 9.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>

## 10 Next Meeting and Adjournment